



# Electronic Filing System (EFS) Data

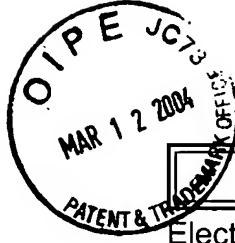
## Electronic Patent Application Submission

### USPTO Use Only

EFS ID: 57019  
Application ID: 10706468   
Title of Invention: SEMICONDUCTOR PACKAGE  
WITH CHAMFERED CORNERS  
AND METHOD FOR  
MANUFACTURING THE SAME  
First Named Inventor: Sung Yang  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2003-11-12  
Effective Receipt Date: 2004-03-12  
Submission Type: Information Disclosure  
Statement  
Filing Type:  
Confirmation number: 6744  
Attorney Docket Number: AMKOR095A

Total Fees Authorized:

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## TRANSMITTAL

Electronic Version v1.1  
Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS AND METHOD FOR MANUFACTURING THE SAME	
Application Number:	10/706468 	
Date:	2003-11-12	
First Named Applicant:	Sung Jin Yang	
Confirmation Number:	6744	
Attorney Docket Number:	AMKOR095A	
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>		
Submitted by:	Elec. Sign.	Sign. Capacity
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney
Documents being submitted us-ids	Files ids5-usidst.xml us-ids.dtd us-ids.xsl	
Comments		

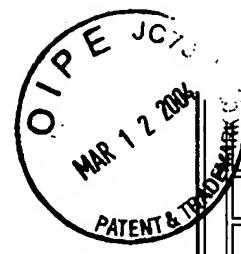


## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS AND METHOD FOR MANUFACTURING THE SAME				
Application Number:	10/706468 				
Confirmation Number:	6744				
First Named Applicant:	Sung Yang				
Attorney Docket Number:	AMKOR095A				
Art Unit:	2811				
Search string:	( 6194777 or 6198171 or 6197615 or 6201292 or 6201186 or 6204554 or 6208023 or 6208021 or 6208020 or 6211462 or 6218731 or 6222258 or 6225146 or 6229205 or 6229200 or 6239384 or 6239367 or 6242281 or 6256200 or 6258629 or 6282095 or 6281568 or 6281566 or 6285075 or 6291273 or 6291271 or 6294830 or 6294100 or 6297548 or 6295977 or 6303997 or 6303984 or 6307272 or 6309909 or 6316838 or 6316822 or 6323550 or 6326678 or 6326244 or 6326243 or 6335564 or 6337510 or 6339255 or 6348726 or 6355502 or 6369454 or 6369447 or 6373127 or 6380048 or 6384472 ).pn.				
US Patent Documents					
Note: Applicant is not required to submit a paper copy of cited US Patent Documents					
init	Cite.No.	Patent No.	Date	Patentee	Kind
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	2	6198171	2001-03-06	HUANG ET AL	Subclass
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50	6384472	2002-05-07	HUANG

Signature

Examiner Name	Date